

DIELECTRIC RESIN COMPOSITION AND MULTILAYER CIRCUIT BOARD  
COMPRISING DIELECTRIC LAYERS FORMED THEREFROM

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ABSTRACT OF THE DISCLOSURE

10 A dielectric resin composition comprising at least one type of epoxy resin and at least one type of cyanate ester which would react with said epoxy resin, together with a metal ion catalyst system, the ratio of the epoxy functional groups of said epoxy resin to the cyanate groups of said cyanate ester being in the range of from 1:0.8 to 1:1.4. Alternatively, a dielectric resin composition according to the invention may comprise a polyimide resin with side chain epoxy groups, a cyanate ester with two or more cyanate groups in the molecule, and a metal ion catalyst system. A multilayer circuit board having a multilayer structure comprising a core substrate and a required number of dielectric layers and wiring layers stacked alternately, wherein at least one of the dielectric layers is formed from a dielectric resin composition of the invention, is also disclosed.

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